

AMENDMENTS TO THE SPECIFICATION:

Please delete the paragraph at page 26, lines 25-34, and substitute therefore the following new paragraph:

--The second invention of the present invention is explained below. In the second invention of the present invention, a cyanate ester compound having 2 or more cyanate groups in the molecule and/or a prepolymer thereof is/are Component (a), an epoxy resin containing at least one kind of an epoxy resin having a biphenyl structure in the molecule is Component (b) (d), a polyphenylene ether resin is Component (c), a monovalent phenol compound is Component (d) (b), a flame retardant is Component (e), and an antioxidant is Component (f).--

Please delete the paragraph at page 60, lines 17 and 18, and substitute therefore the following new paragraph:

--Evaluating methods of characteristics of the copper clad laminated boards are as ~~mentioned below~~ mentioned above.--

Please delete the paragraph at page 79, lines 4-13, and substitute therefore the following new paragraph:

--In the same manner as in Example 17 except for removing 2,6-di-tert-butyl-4-methylphenol (TBMP), and formulating a bisphenol A type epoxy resin (DER-331L, available from Dow Chemical) in place of 3,3', 5,5'-tetra-methylbiphenol diglycidyl ether with a formulation amount as shown in Table ~~3~~ 7, and methyl ethyl ketone was so formulated in a formulation amount that a non-volatile concentration became about 55% by weight, the procedure was carried out as in Example 17 to prepare a resin varnish having the non-volatile concentration of about 55% by weight.--